

Technical Data Sheet

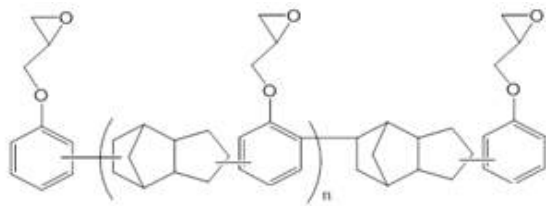
KES-7680M75

DCPD-Phenol Epoxy

General Description

DCPD-苯酚環氧樹脂KES-7680M75是衍生自双環戊二烯和苯酚的環氧樹脂。KES-7680M75是溶於25wt%MEK的溶液產品。因為它具有優異的電氣性能，KES-7680M75設計用於高性能的半導體EMC及CCL。特別是該產品具有低Dk (介電常數) 和Df (低介電損耗) 特性，因此可用於高速PCB。

Chemical Structure



Resin Properties

Property	Typical values
EEW (g/eq)	255 ~ 290
S.P. (°C)*	75 ~ 85
Hy-Cl (ppm)	500 Max
N.V.(wt.%)*	75±1

* Mettler 2°C/min

Usage

1. CCL laminate for high speed PCB
2. Carbon fiber prepreg laminate
3. Electronic encapsulation and transfer molding
4. Electrical heat resistance molding compound
5. Lead free type CCL laminate varnish additives
6. High temperature adhesives and structural composites
7. Tooling, casting & molding compounds

Storage

Keep in cool, dry, ventilate condition and in closed containers.

Keep away from heat sources and direct sunlight. Recommended safe handing procedures are discussed in the information on the MSDS should reviewed and understood before working.

Packaging

Can of 20kg net weight

Drum of 200kg net weight